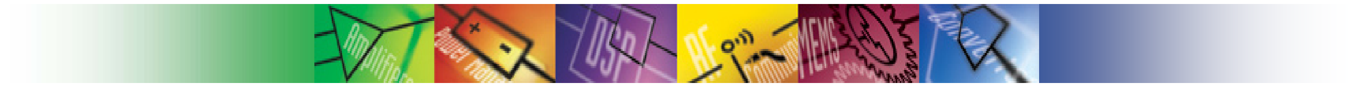

Materials Declaration

Package	CSP BGA
Body Size	15 X 15 X 1.85 (4 layers)
Ball Count	196
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.5	2.57 E-01	277711
Epoxy resin	12.7	3.84 E-02	41497
Antimony Trioxide	0.5	1.48 E-03	1596
Brominated Epoxy Resin	0.3	8.85 E-04	958

Molding Compound

Item	PPM	Method
Pb	8.2	US EPA #3052
Cd	Not Detected	US EPA #3052
Hg	Not Detected	US EPA #3052
Cr+6	Not Detected	US EPA #3060A
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Laminate

Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	46.6	1.62 E-01	175463
Copper	41.3	1.44 E-01	155684
Solder Mask	6.2	2.17 E-02	23446
Brominated Compound	3.2	1.11 E-02	11997
Nickel	2.2	7.79 E-03	8434
Gold	0.4	1.41 E-03	1522

Die Attach Paste

Item	PPM	Method
Pb	3.1	US EPA #3052
Cd	Not Detected	US EPA #3052
Hg	Not Detected	US EPA #3052
Cr+6	Not Detected	US EPA #7196A and #3060A
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Solder Ball

	% of Plating	Weight (g)	PPM
Sn	63.0	1.55 E-01	167200
Pb	37.0	9.08 E-02	98197

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.9	4.64 E-03	5021

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	2.57 E-02	27862

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	78.0	2.46 E-03	2662
Resin	22.0	6.94 E-04	751

Package Totals

Weight (g)	PPM
9.24 E-01	1000000

AMK-BC-I

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

03/08/06